From	To	Room/Event		
Time		**Day 1: Monday — October 7, 2024**		
3:00PM	6:00PM	Location: California Ballroom Foyerr, Mezzanine Level		
		Registration Opens		
6:30PM	8:30PM	Location: TBD		
		Leadership Dinner - By invitation Only		

Time		Day 2: Tuesday — October 8, 2024		
From	**To**	**Room/Event**		
7:45AM	8:00AM	Room: California DE		
		InterPACK'24 -Opening Remarks by Prof. Pradeep Lall		
8:00AM	8:45AM	Room: California Ballroom , Salons FGHJ		
		OUSD IBAS RESHAPE Project - Matthew Walsh		
8:45AM	9:30AM	The Use of Additive Hybrid Electronics as a Key Element in the National Strategy for Advanced Packaging -		
9:30AM	10:45AM	Room: Califnornia Ballroom, Salon C	Room: California Ballroom, Salon B	Room: California Ballroom, Salon K
		03-01: Electronics Packaging - Electrical Design	02-01: Data Centers and Modular Edge Systems - I	07-01: Transportation Systems, AI and Machine Learning - I
10:45AM	11:00AM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer		
11:00AM	12:15PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon L	Room: California Ballroom, Salon M
		03-02: Electronics Packaging - Components	04-01: Power/RF Electronics and Photonics - I	06-01: FHE Design & Reliability

From	To	Room/Event		
12:15PM	1:30PM	Room: California Ballroom, Salons FGHJ Lunch: Avram Bar-Cohen Award		
1:30PM	2:15PM	Room: California Ballroom, Salon D Passive Two-Phase Cooling of Electronics and Energy Efficiency		Room: California I Efficient Ene
2:15PM	2:30PM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer		
2:30PM	3:45PM	Room: California Ballroom, Salon C 03-04: Electronics Packaging - Stress and Reliability - I	Room: California Ballroom, Salon B 02-02: Data Centers and Modular Edge Systems - II	Room: California Ballroom, Salon L 04-02: Power/RF Electronics and Photonics - II
3:50PM	5:15PM	Room: California Ballroom, Salon C 03-05: Electronics Packaging - Stress and Reliability- II	Room: California Ballroom, Salon M 06-02: Advanced Materials & Processes for Printed Electronics - I	Room: California Ballroom, Salon K K16 Mentorship
		Room: California Ballroom, Salon L Short Course - Efficient Thermal Simulations Using Compact Models		
5:45PM	6:45PM	Room: Salon San Jose Ballroom Interactive Poster Session		
7:00PM	7:30PM	Room: California Ballroom, Salon D K-16 Committee Meeting (Open)		
7:30PM	8:00PM	Room: California Ballroom, Salon D K-16 Committee Meeting (Closed)		

Time		Day 3: Wednesday — October 9, 2024
From	To	Room/Event
8:00AM	8:45AM	Room: California Ballroom , Salons FGHJ

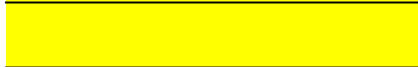
Start	End			
8:00AM	8:45AM	SRC's Microelectronics and Advanced Packaging Technologies (MAPT) Roadmap: Driving a New Era of Innovation in Semicond		
8:45AM	9:30AM	2.5D/3D Integration for High-Speed Light Engines - Radha Nagarajan		
9:30AM	10:45AM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon A	Room: California Ballroom, Salon M
		03-06: Electronics Packaging - Stress and Reliability - III	01-01: Heterogeneous Integration	06-04: Materials & Processes for RF Electronics
10:45AM	11:00AM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer		
11:00AM	12:15PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon B	Room: California Ballroom, Salon M
		03-07: Electronics Packaging - Stress and Reliability - IV	02-03: Data Centers and Modular Edge Systems - III	06-05: FHE Applications & Processing
12:15PM	1:30PM	Room: California Ballroom, Salons FGHJ		
		Lunch: InterPACK'24 Allan Kraus Award		
1:30PM	2:15PM	Room: California Ballroom, Salon D		Room: California
		Size and Timescale Matching for Transient-Aware Thermal Management		AI/ML and Ind
2:15PM	2:30PM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer		
2:30PM	3:45PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon B	Room: California Ballroom, Salon K
		03-08: Electronics Packaging - Reliability	02-04: Data Centers and Modular Edge Systems - IV	07-03: Transportation Systems, AI and Machine Learning - III
3:50PM	5:15PM	Room: California Ballroom, Salon L	Room: California Ballroom, Salon M	Room: California Ballroom, Salon C
		05-03: Multiscale Thermal Transport and Energy Storage - III	06-06: Advanced Materials & Processes for Printed Electronics - II	03-09: Electronics Packaging - Thermal - I
6:00PM	6:30PM	Room: California Ballroom, Salon D		
		InterPACK Meeting (Closed)		

6:30PM	7:00PM	Room: California Ballroom, Salon D		
		InterPACK Meeting (Open)		
7:00PM	7:30PM	Room: California Ballroom, Salon D		
		EPPD Meeting (Open)		

Time		Day 4: Thursday — October 10, 2024		
From	To	Room/Event		
8:00AM	8:45AM	Room: California Ballroom , Salons FGHJ		
		ARPA-E COOLERCHIPS Technology for a Future of Energy Efficient High Power Density/AI Data Centers - Pet		
8:45AM	9:30AM	Data Center Industry's Supply Chain Readiness and Scalability for Liquid Cooling - Ani Natekar		
9:30AM	10:45AM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon L	Room: California Ballroom, Salon B
		03-10: Electronics Packaging - Thermal - II (Two-phase)	05-01: Multiscale Thermal Transport and Energy Storage - I	02-05: Data Centers and Modular Edge Systems - V
10:45AM	11:00AM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer		
11:00AM	12:15PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon L	Room: California Ballroom, Salon B
		03-11: Electronics Packaging - Thermal - III	05-02: Multiscale Thermal Transport and Energy Storage - II	02-07: Data Centers and Modular Edge Systems - VII
12:15PM	1:30PM	Room: California Ballroom, Salons FGHJ		
		Lunch: ASME Worcester Reed Warner Medal + InterPACK'24 Awards (Nasser Grayeli Poster, EPPD, JEP)		
1:30PM	2:15PM	Room: California Ballroom, Salon D		Room: California I
		Wearable Ultrasound Technology		Additive Manufacturing for Electr
2:15PM	2:30PM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer		

2:30PM	3:45PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon B	Room: California Ballroom, Salon M
		03-12: Electronics Packaging - Thermal IV (Single Phase Convection)	02-06: Data Centers and Modular Edge Systems -VI	06-07: FHE Printing & Packaging
3:50PM	5:15PM		Room: California Ballroom, Salon K	
			07-02: Transportation Systems, AI and Machine Learning - II	

- Art Wall
Room: California Ballroom, Salon A
Reliability of Additively Manufacturing Flexible and Stretchable Electronics – Experiments, Models, and Applications
Room: California Ballroom, Salon A
Data Center and Telecom Challenges and Opportunities



Ballroom, Salon E

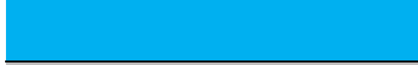
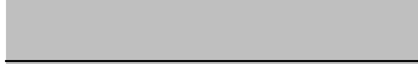
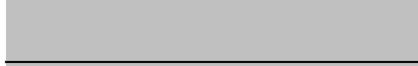
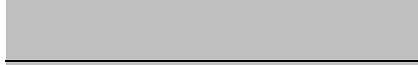
rgy Systems

Room: California Ballroom, Salon A

Machine Learning for Electronics

Room: California Ballroom, Salon A

Women in Engineering

luctors and Digital Twins - TBD
Room: Salon K
Liquid-Cooling and Heat Reuse Technologies
Room : California Ballroom, Salon K
Advancing Electronics Packaging and Heterogeneous Integration: Insights from Interpack 2024
Ballroom, Salon E
lustry Trends
Room : California Ballroom, Salon A
Thermal/Mechanical/Electrical Challenges and Opportunities for Mobile/Wireless/AI/IoT/Automotive and Higher Power Computing Devices

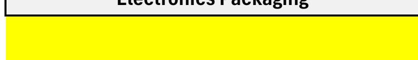
ter de Bock

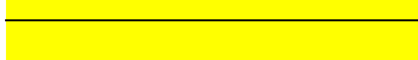
Room: California Ballroom, Salon M

Status, Challenges, and Opportunities in Electronics Packaging from a Government/Lab Perspective

Room: California Ballroom, Salon M

Additive Manufacturing for Domestic Electronics Packaging





Ballroom, Salon E

ronic Devices and Interconnects

Room: California Ballroom, Salon A
Two-phase Flow for Electronics Cooling
Room: California Ballroom, Salon M
06-03: Printed Electronics for Wearables & Health

Type
ASME Meetings

Type
ASME Meetings
Plenary Speaker
Technical Sessions
Workshops
Technical Sessions
Panel

Lunch Presentations
Track Keynotes
Tutorials
Technical Sessions
Panel
Technical Sessions
Workshops
Short Course
Student Posters
ASME Meetings
ASME Meetings

Type

Plenary Speaker
Technical Sessions
Tutorials
Technical Sessions
Workshop
Lunch Presentations
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